DATA SHEET



# MB88200 SERIES CMOS Low-end Single-chip 4-bit Microprocessor

#### DESCRIPTION

The Fujitsu MB88200 series CMOS single-chip 4-bit microcomputer family is an economical low-end version of the conventional MB8850 series. It is designed based on the MB8850 series architecture, and its instruction set is a subset of the MB8850 series. But some of the on-chip resources available on the MB8850 series are eliminated for low-cost, high-volume applications, and a few new mask options are added for wider application.

The MB88200 series consists of the MB88201 and MB88202. Both devices contain a program memory (mask ROM: 512 x 8 bits for MB88201, 1K x 8 bits for MB88202), a data memory (static RAM: 16 x 4 bits for MB88201, 32 x 4 bits for MB88202), and I/O port (up to 12 lines), and a clock generator.

This series has two supply versions. One is standar dversion (4.5 V to 5.5 V), another is A-version (3.5 V to 6.0 V).

They are fabricated by the silicon-gate CMOS process and packaged in a 16-pin plastic DIP (suffix -P) or 16-pin plastic flat package (suffix -PF).

They operate with a single +5 V power supply and a 2 MHz clock without a prescaler (or 4MHz clock with prescaler) over the temperature range of -40 to +85 °C (standard version) or -30 to +70 °C (A-version).

CMOS technology allows the device to operate with low power dissipation (1mA typ. at  $V_{CC}$ =5 V and fc=1 MHz), and further the standby function (if implemented) enables data retention with lower current 10  $\mu$ A max. at  $V_{CC}$ =3.5 V).

For development of the MB88200 series-based system by the user, Fujitsu provides the MB88200 cross-assembler and host-emulator which run on the PC-DOS machines, the MB2115 series evaluation tool system. These development tools enable users to minimize their development time and cost.



16-Pin Plastic DIP (DIP-16P-M04)

> Order Nos: MB88201-P MB88202-P



16-Pin Plastic Flat Package (FPT-16P-M03)

> Order Nos: MB88201-PF MB88202-PF

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields. However, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum rated voltages to this high impedance circuit.

#### **Features**

- CMOS Low-end Single-chip 4-bit Microcomputer
- Program Memory:
  - o MB88201: 512 x 8-bit mask ROM o MB88202: 1K x 8-bit mask ROM
- Data Memory:
  - o MB88201: 16 x 4-bit static RAM
  - o MB88202: 32 x 4-bit static RAM
- 10 to 12 Lines (depending on oscillator and standby function options) I/O Port:
  - o R-Port: Up to three 4-bit parallel or 12 individual input/output ports
- Four Selectable Output Port Types for R-Port with Mask Option:
  - Standard pull-up
  - o Standard open-drain
  - o Middle-current open-drain
  - o 12V-interface open-drain (R4 to R7)
- On-chip Clock Generator with Four Mask Options:
  - o Crystal/ceramic resonator
  - o RC-network
  - Capacitor
  - o External clock drive
- Mask-option Divide-by-two Clock Prescaler for Expanding Clock Range
- Nesting Level:
  - o MB88201: 2 levels
  - o MB88202: 4 levels
- Instruction Set: Subset of MB8850 series
  - : 37 (MB88201) or 38 (MB88202) Number of instructions

  - o Instruction length/cycle : 1 byte/1 cycle or 2 byte/2 cycle
  - : 3.0µs min. using 2MHz clock without prescaler(or 4MHz clock with prescaler) Execution time
- On-chip Power-on Reset Circuit
- Mask Option Standby Function: Software initiation & hardware release
- Mask Option Low-voltage Reset Function (Standard version only)
- Mask Option Output Port Level During Reset:
  - o High Level
  - o Low level (R0-R3, R5, R6, R10, R11)
- Low Power Dissipation:
  - o 1mA typ. at Vcc=5.0V, fc=1MHz (Active mode)
  - 10μA max. at Vcc=3.5V, fc=0MHz (Standby mode)
- Single Power Supply:
  - o Standard version:
    - o 4.5V to 5.5V (Active mode)
    - o 3.5V to 6.0V (Standby mode)
  - o A-version:
    - o 3.5V to 6.0V (Active mode)
    - o 3.0V to 6.0V (Standby mode)

## Features (continued)

- Wide Operating Temperature Range:
  - Standard version:
    - TA=-40°C to +85°C (without low-voltage reset function)
    - o TA=-10°C to +70°C (with low-voltage reset function)
  - o A-version:
    - o TA=-30°C to +70°C
- Silicon—gate CMOS Process
- Powerful Development Support:
  - o PC-DOS cross-assembler(SM07620-AXXX)
  - o PC-DOS host emulator software for monitoring evaluation board and symbolic debugging (SM07620-GXXX)
  - o MB2115 series evaluation tool (MB2115-01, -02, -04, and -33A) for software debugging
- Package and Ordering Information
  - o 16-pin plastic DIP, order as MB8820XP, or
  - o 16-pin plastic SOP, order as MB8820XPF

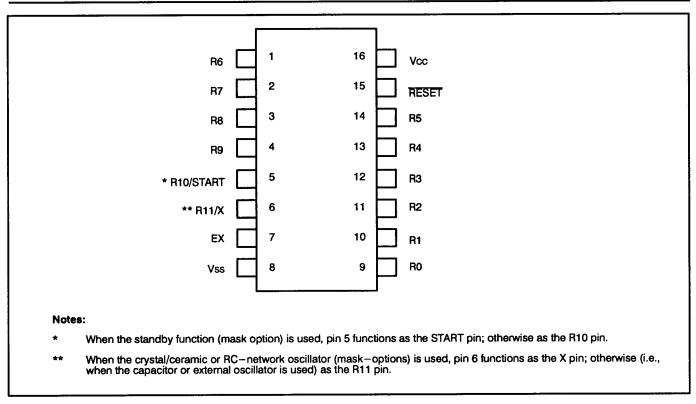


Figure 1. Pin Assignment

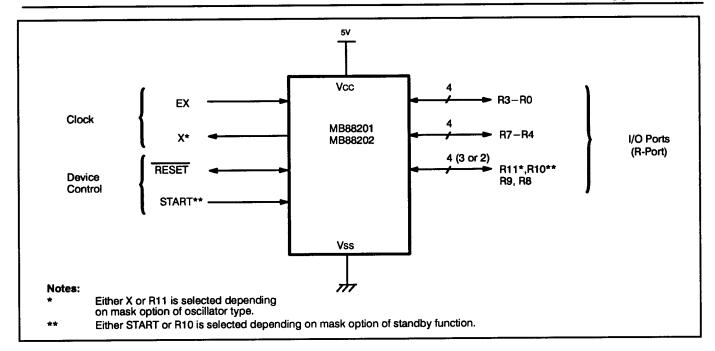


Figure 2. Logic Symbol

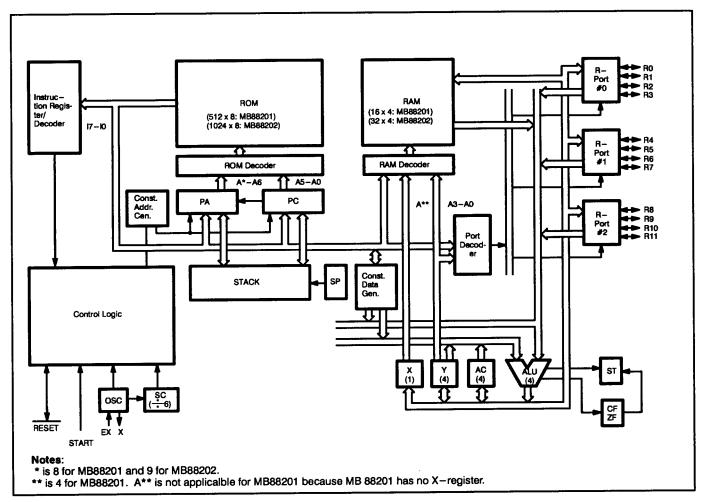


Figure 3. Block Diagram

# **Pin Description**

Fig. 1 and Table 1 show the pin assignment and pin description of the MB88200 series.

Table 1 Pin Description

Symbol	Pin No.	Туре	Name and Function
Power S	upply		
Vcc	16	_	+5V DC power supply pin.
Vss	8	<del>-</del>	Ground pin.
Clock			
EX	7	l	Oscillator Input: Input to the inverting amplifier that forms the on—chip oscillator. An external crystal/ceramic resonator or RC—network is connected between the EX and X pins, or an external capacitor or external oscillator is connected to the EX pin. One of these four oscillator types can be selected using mask option.  This pin is a non—hysteresis input when the crystal/ceramic resonator or external oscillator is selected, or a hysteresis input when the RC—network or capacitor oscillator is selected.
х	6	0	Oscillator Output: Output of the inverting amplifier that forms the on—chip oscillator, and input to the internal clock generator. An external crystal/ceramic resonator or RC—network is connected between the EX and X pins.  The X pin is common to the R11 pin. Either of them is selected using mask option. The X pin is selected when the crystal/ceramic resonator or RC—network oscillator is implemented.
Device C	Control		
RESET	15	I/O	Reset: This pin functions as an external reset input or power—on/low—voltage reset output. External reset input: A reset input to the internal reset circuit. A low level on the RESET pin forcedly stops the MCU's operations, and initializes its internal state. After the RESET pin returns high, the MCU restarts execution of program from address #0. The RESET pulse must be low for at least two instruction cycles (12 clock periods: approximately 6µs using a 2MHz crystal without a prescaler) while the oscillator is stably running after power on. An external capacitor (and an internal pull—up resistor) or RC—network, whose time constant should be greater than the reset time required (12 clock periods), composes the external reset circuit. This pin is active even in the standby mode.  This pin is a hysteresis input with an internal pull—up resistor.  Power—on/low—voltage reset output: A reset output from the on—chip reset control circuit. Normally this output is high during the active operation, except power—on/low—voltage reset.

Table 1 Pin Description (continued)

Symbol	Pin No.	Type	Name and Function
Device C	ontrol (conti	nued)	
RESET	15	1/0	<ol> <li>Power—on reset output: The rising of the Vcc voltage after power on outputs a negative pulse to the RESET pin. With an external RC—network at the RESET pin, whose time constant should be greater than the reset time required (the oscillator stabilization time, plus 12 clock periods), the power—on reset circuit is composed.</li> <li>Low—voltage reset output (Standard version only): The RESET pin outputs a low level when the Vcc voltage lowers below a threshold voltage during the active operating mode, and returns high when the Vcc voltage recovers above the threshold voltage. With an external RC—network at the RESET pin, whose time constant should be greater than the reset time required (the oscillator stabilization time, plus 12 clock periods), the low—voltage reset circuit is provided. (The low—voltage reset function is mask optional, and is disabled during the standby mode).</li> </ol>
START	5		Start: A standby release input to the on—chip standby control circuit. A high level on the START pin triggers the standby release sequence to release the MCU from the standby mode. Before applying START pulse, the Vcc voltage must return to the active operation range (4.5V to 5.5V)when the battery backup is used. The START pin must remain high until the oscillation becomes stable after the oscillator restarts. An external RC—network at the START pin, whose time constant should be greater than the oscillator stabilization time, composes the external standby release circuit. This pin is inactive during reset and for two instruction cycles after the standby initiation.  This pin is a hysteresis input with an internal pull—down resistor.  The START pin is common to the R10 pin. Either of them is selected using mask option. The START pin is selected when the standby function is implemented. Even in that case, the "output" port of R10 is internally still alive, and is connected to the internal standby control circuit. The falling edge on the "internal" R10 output, which is given by software (OUT or SETR/RSTR instructions), triggers the standby initiation sequence.

Continued on next page

Table 1 Pin Description (continued)

Symbol	Pin No.	Туре	Name and Function
I/O Port			
R3-R0, R7-R4, R11-R8	12-9 2,1,14,13 6-3	I/O	R-Port: This port functions as three 4-bit parallel input (non-latched)/output (latched) ports, or 12 individual input (non-latched)/output (latched) lines, depending on instructions.  Parallel I/O: Each 4-bit port is named R-Port #0 (R3-R0), R-Port #1 (R7-R4), and R-Port #2 (R11-R8), and is indirectly addressed by the Y-register (Port #). 4-bit data in the accumulator is output to an addressed port of R-Ports #0 to #2 by OUT instruction. 4-bit data on the addressed port is input into the accumulator by IN instruction. (Before IN instruction, the port to be addressed must be set up to "1" (input mode)).  Individual I/O: Each line from R11 to R0 is indirectly addressed by the Y-register (Bit #). An addressed line is individually set/reset by SETR/RSTR instruction, and is individually testable using TSTR instruction. (Before TSTR instruction, the line to be addressed must be set up to "1" (input mode)).  Refer to Table 3 User mask options for available making options.  The R10 pin is common to the START pin. Either of them is selected using mask option. When no standby function is implemented, the R10 pin is selected.  The R11 pin is common to the X pin. Either of them is selected using mask option. When the capacitor oscillator is implemented or when the external oscillator is used, the R11 pin is selected.

# **Input/Output Circuits**

All input—only pins are internally pulled up, and R—Port can have push—pull (standard pull—up) or open—drain (standard, middle—current, 12V—interface) buffer using mask option.

Table 2 Input/Output Circuits

Pin	Circuit	Remarks
EX, X	Crystal/Ceramic Oscillation	Non-hysteresis inverter
	EX PHILIPPIN X	<ul> <li>Feedback resistor:Approx. 2MΩ typ. (at Vcc = 5V)</li> <li>Pin 6 = X (not R11)</li> </ul>
	RC-Network Oscillation	Hysteresis inverter
		Without feedback resistor
	× 🗆	● Pin 6 = X (not R11)
	C-Network Oscillation	Hysteresis inverter
		<ul> <li>Feedback resistor: Approx. 5kΩ typ. (at Vcc = 5V)</li> <li>Pin 6 = R11 (not X)</li> </ul>
	External Clock Drive	Non-Hysteresis inverter
	EX 🗆	<ul> <li>Without feedback resistor</li> <li>Pin 6 = R11 (not X)</li> </ul>
RESET	Input/Output Pin  EX	<ul> <li>Hysteresis inverter</li> <li>Output pull−up resistor (P−ch. Tr.): Approx. 300kΩ typ. (at Vcc = 5V)</li> </ul>

Table 2 Input/Output Circuits (Continued)

Pin	Circuit	Note
R-Port	Input/Output Pin	<ul> <li>Non-hysteresis inverter</li> <li>Output port option         <ol> <li>Standard pull-up:</li></ol></li></ul>
START	Input Only Pin	<ul> <li>Hysteresis inverter</li> <li>Input pull – down resistor (N-ch. Tr.) : A pprox. 300kΩ typ. (at Vcc = 5V)</li> </ul>

# **User Mask Options**

The MB88200 series has the following mask options, which must be specified by the customer on the attached data release form when devices are ordered.

**Table 3 User Mask Options** 

Optional Fea- ture			Option No.	Note
Program ROM	_	User program	_	1. MB88201: 512 x 8 bits 2. MB88202: 1024 x 8 bits
Clock Prescaler	CLK	No	0	fc= 0.5MHz to 2MHz
		Yes	1	fc= 1 MHz to 4MHz
Oscillator Type	osc	Crystal/Ceramic oscillation	0	Pin 6 functions as X.
		RC-network oscillation	1	Pin 6 functions as X.
	-	Capacitor oscillation	2	Pin 6 functions as R11.
		External clock drive	3	Pin 6 functions as R11.
Output Port Type*	PORT	Standard pull-up	3/M	Pull-up resistor is approx. 10k $\Omega$ . R0 to R3, and R9 are standard open-drain.
		Standard open-drain	2/L	
		Middle-current open-drain	1/K	10mA
		12V-interface open-drain	4/G	<ol> <li>For R4-R7 only, and R4-R7 are output only.</li> <li>Other R-Ports are standard open-drain.</li> </ol>
Output Port Level	RST	High level	0	
During Reset **		Low level	1	Except R4, R8, and R9: R4, R8, and R9 are fixed high.
Low-Voltage	PWR	No	1	Ta=-40°C to + 85°C
Reset Function		Yes	2	Ta=-10°C to + 70°C
Standby Function	STBY	No	0	Pin 5 functions as R10.
		Yes	1	Pin 5 functions as START.

#### Notes:

- \* Only one of the four options can be selected. Mixed options are not permitted.
- \*\* Either "high level" or "low level" is applied to all R-Ports in a clump. Mixed options are not permitted.

## **Instruction Set Description**

The MB88200 series instruction set includes 37 (MB88201) or 38 (MB88202) instructions, 95% of which are single—byte and single—cycle, and 5% two—byte and two—cycle. The MB88200 series instruction set is a subset of the MB8850 series. It is divided into eight functional groups:

- Register-to-register transfer
- Register-to-memory transfer
- Constant transfer
- · Arithmetic and logical operations
- Bit manipulation
- Input/Output
- Branch
- Flag manipulation

Tables 4 and 5 summarize the MB88200 series instruction set.

**Table 4 Instruction Set Summary** 

Table 4 Instruction Set Summary										
	Mnemonic		Code	Flag/			Byte/	Operation		
	+Opera	ana	(Hex.)	ZF CF ST		31	Cycle			
Register-to-	TAY		04	•	•	•	1/1	Y←(AC)		
Register	TYA		14	‡	•	•	1/1	AC+-(Y)		
Transfer					İ					
Register-to-	L		0D	‡	•	•	1/1	AC←{M(X,Y)}		
Memory	ST		1D	•	•	•	1/1	M(X,Y)←(AC)		
Transfer	XD	D	50-53*	‡*1	•	•	1/1	$(AC)$ $\rightleftharpoons$ $\{M(0,D)\}; D=0 \text{ to } 3$		
	XYD	D	54-57*	1*2	•	•	1/1	$(Y) \pm \{M(0,D)\}; D=4 \text{ to } 7$		
Constant	CLA		90	Į.	•	•	1/1	AC←0 (Included in LI instruction)		
Transfer	LI	imm	90-9F*	l ‡	•	•	1/1	AC←imm; imm=0 to 15		
	LXI	imm	58-59*	li	<b>  •</b>	•	1/1	X3 to X1+-0, X0+-imm; imm=0 or 1 *3		
	LYI	imm	80-8F*	l t	<b>  •</b>	•	1/1	Y←imm; imm=0 to 15		
Arithmetic	ADC		0E	1	1	ŢĊ	1/1	AC←(AC)+{M(X,Y)}+(CF)		
& Logical	Al	imm	70-7F*	İ	🛊	↓c	1/1	AC+-(AC)+imm; imm=0 to 15		
Operations	С		2E	‡	‡	ĻΖ	1/1	{M(X,Y)}-(AC)		
•	CI	imm	B0-BF*	Ιį	‡	↓z	1/1	imm-(AC); imm=0 to 15		
	CYI	imm	A0-AF*	Ιį́	‡	↓z	1/1	imm-(Y): imm=0 to 15		
	DCA		7F	<b>‡</b>	‡	ļс	1/1	AC←(AC)+15 (Included in Al instruction)		
	DCM		19	l t	•	ŢC	1/1	$M(X,Y) \leftarrow \{M(X,Y)\} - 1$		
	DCY		18	li	•	ŢC	1/1	Y←(Y)−1		
	ICA		71	1	‡	ŢC	1/1	AC←(AC)+1 (Included in Al instruction)		
	ICM		09	į	•	ţc	1/1	$M(X,Y) \leftarrow \{M(X,Y)\} + 1$		
	ICY		08	Ì	•	ţc	1/1	Y←(Y)+1		
	NEG		2D	•	•	JZ	1/1	AC←(AC)+1		
	SBC		1E	İ	‡	Ţc	1/1	$AC \leftarrow \{M(X,Y)\} - (AC) - (CF)$		
Bit	RBIT	bp	34-37*	•	•	•	1/1	$\{M(X,Y)\}bp\leftarrow 0$ ; $bp=0$ to 3		
Manipulation	SBIT	bp	30-33*	•		•	1/1	$\{M(X,Y)\}$ bp $\leftarrow$ 1; bp=0 to 3		
	TBA	bp	4C-4F*	•	•	ŢC	1/1	(AC)bp-1; bp=0 to 3		
	TBIT	bp	38-3B*			Ĭc	1/1	$\{M(X,Y)\}bp-1$ ; $bp=0$ to 3		
Input/	IN		13	‡	•	•	1/1	AC+-(R)Y; Y=0 to 2 (Port #)		
Output	OUT		03			•	1/1	(R)Y←(AC) ; Y=0 to 2 (Port #)		
	RSTR		22	•	•	•	1/1	(R)Y←0; Y=0 to 11		
	SETR		20			•	1/1	(R)Y←1; Y=0 to 11		
	TSTR		24	•	•	ŢC	1/1	(R)Y -1; Y=0 to 11		

Table 4 Instruction Set Summary (continued)

	Mnemonic	Code	Flag	Flag/Status		Byte/	Operation		
	+Operand	(Hex.)	ZF CF		ST	Cycle			
Branch	CALL addr	6000 – 63FF*	•	•	•	2/2	If ST=1, Subroutine Call for addr; addr=0 to 1023 ST=0, Not Subroutine Call.		
	NOP	00	•	•	•	1/1	No operation		
	JMP addr	C0-FF*	•	•	•	1/1	If ST=1, Branch to addr; addr=0 to 63 ST=0, Not Branch		
	JPL addr	6800 – 6BFF*	•	•	•	2/2	If ST=1, Branch to addr; addr=0 to 1023 ST=0, Not Branch;		
	RTS	2C	•	•	•	1/1	Return From Subroutine		
Flag	RSTC	23	•	1	•	1/1	CF←0		
Manipulations	SETC	21	•	†	•	1/1	CF4—1		
	TSTC	28	•	•	↓CF	1/1	(CF)-1		
	TSTZ	29	•	•	↓ZF	1/1	(ZF) – 1		

#### Notes:

- Code is variable depending on the operand.
- \*1: ZF is set or reset depending on contents of AC after instruction execution.
- \*2: ZF is set or reset depending on contents of Y after instruction execution.
- \*3: This instruction is available for MB88202 only because MB88201 has no X-register.

# **Symbols and Abbreviations**

Symbols Meaning	
+ Is exchanged with + Arithmetic plus - Arithmetic minus - (Overline) Negation	
+ Arithmetic plus - Arithmetic minus - (Overline) Negation	
<ul><li>Arithmetic minus</li><li>(Overline)</li><li>Negation</li></ul>	
— (Overline) Negation	
Set to "1" always	
Set to "0" always	
Set to "0" always      Affected (set or reset) by operation results  ↓C      Set to "0" due to carry (not carry flag)	
C Set to "0" due to carry (not carry flag)	
↓CF Set to "0" due to carry flag	
↓Z Set to "0" due to zero (not zero flag)	
↓ZF Set to "0" due to zero flag  • Not affected	
• Not allected	
Abbreviations Meaning	
AC Accumulator	
addr Jump address	
bp Bit pointer (that is part of the instruction code)	
C Carry	
CF Carry flag	
D Direct data memory address (that is part of the instruction code)	
imm Immediate data	
LSB Least significant bit  M(X,Y) Data memory (RAM) location indirectly addressed by data pointer (X – and Y – registers)	
market at the state of the stat	#0 (X=0)
M(0,D) Data memory (RAM) location directly addressed by "D" bits in the instruction code, in page MSB Most significant bit	
R R-Port (#0: R3-R0, #1: R7-R4, #2: R11-R8)	
(R)Y; Y=n (1) R-Port #n specified by Y-register (Y=0 to 3)	
(2) R-Port bit n specified by Y-register (Y=0 to 11)	
ST Status flag	
χ X-register (that indicates page # in data memory RAM)	
Xn The n-th bit of X-register	
Y Y-register	
Z Zero	
ZF Zero Flag	

## **Table 5 Instruction Code Summary**

L	0	1	2	3	4	5	6	7	8	9	A	В	С	D	E	F
0	NOP			OUT	TAY				ICY	ICM				L	ADC	
1				IN	TYA				DCY	DCM				ST	SBC	
2	SETR	SETC	RSTR	RSTC	TSTR				TSTC	TSTZ			RTS	NEG	O	
3		SE b	BIT op			RE	BIT op			T8	3IT op					
4														TE L	BA op	
5		ΧC	)			>	CYD D		L) in	KI* nm						
6		CAI add	LL Ir						JPL addr							
7		(ICA)						<i>F</i>	N mm							(DCA)
8								L jı	.YI mm							
9	(CLA)							L i	.l mm							
A								i	CYI mm				eu			
В								i	Cl mm							
С																
D	JMP addr															
E																
F																

Notes:	: 1-byte/1-cycle instruction

: 2-byte/2-cycle instruction

\* : For MB88202 only because MB88201 has no X-register.

## **Notes on Operation**

### Prevention Latch-up Against

Latch-up may occur in CMOS devices when a voltage higher than Vcc or lower than Vss is applied to input or output pin, or when a voltage exceeding the absolute maximum ratings is applied between Vcc and Vss pins. If latch-up occurs, the supply current increases greatly, and the device may be thermally destroyed. Therefore, applied voltages should not exceed the maximum ratings.

#### Treatment of Unused Pins

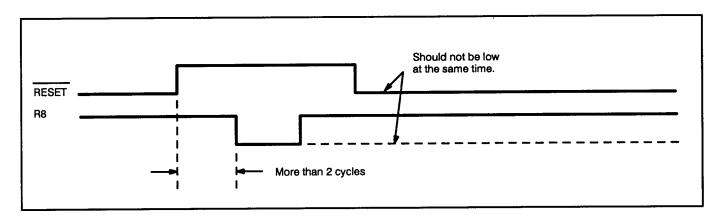
Unused input pins should be externally pulled up or down with resistors because such unused input pins may cause some malfunction if they are left open. (However, the X pin should be open when an external clock oscillator is used.)

#### Special Function of R8 Pin

The R8 pin has another function as a test terminal, in addition to its normal function R – Port. If the R8 pin is forced low while the RESET pin is low, the MCU is placed in the test mode.

Especially when the open—drain is selected for the output port option, the R8 pin should be externally pulled up because such open—drain outputs are left floating and subject to noise disturbance.

At least 2 instruction cycles are required to change R8 pin from high to low after releasing reset (RESET: Low→High)



### Externally Capacitance for Crystal Oscillation

The external capacitors should be adjusted to individual crystal resonators when precise oscillation frequency is required. It is recommended to use a crystal with a frequency higher than the required oscillation frequency, with the divide—by—two prescaler, because crystal resonators with lower oscillation frequency generally tend to have longer stabilization time and wider characteristic variation.

#### Supply Voltage

Malfunction may occur even within the recommended operating supply voltage if the supply voltage changes rapidly. Therefore, the supply voltage should be regulated as well as possible. The following conditions are recommended for the power supply:

- (1) Vcc ripple (peak-to-peak value) at commercial frequency (50Hz to 60Hz): Less than 10% of typical Vcc value.
- (2) Vcc transient change rate (such as a switching of power supply): Less than 0.1V/ms.

# Comparison of the MB8850 Series and MB88200 Series

Table 6 Comparison of the MB8850 Series and MB88200 Series

Device	MB8850 Series	MB88200 Series				
Item						
ROM Size	2048 x 8: MB8851/5, MB8852/6     1024 x 8: MB8854/8	<ul><li>1024 x 8: MB88202</li><li>512 x 8: MB88201</li></ul>				
RAM Size	128 x 4: MB8851/5, MB8852/6     64 x 4: MB8854/8	• 32 x 4: MB88202 • 16 x 4: MB88201				
Register	Total 6:     AC, X, Y, SB, TH, TL	<ul><li>Total 2: AC,Y : MB88201</li><li>Total 3: AC, X, Y: MB88202</li></ul>				
I/O Port	37 lines: MB8851/5     23 lines: MB8852/6, MB8854/8	12-10 lines (Depending on oscillator and standby function options)				
Output Port Type	Standard open—drain output     Standard pull—up output     (Mask Option)	<ul> <li>Standard open—drain</li> <li>Standard pull—up output</li> <li>Middle current open—drain output</li> <li>12V—interface open—drain output* (Mask option) (*R4—R7)</li> </ul>				
Output PLA	• Yes	• No				
Stack Depth (Nesting Level)	• 4 levels	<ul><li>4 levels: MB88202</li><li>2 levels: MB88201</li></ul>				
Timer/Counter	• Yes	• No				
Serial I/O	<ul> <li>Yes: MB8851/5</li> <li>No: MB8852/6,MB8854/8</li> </ul>	• No				
Oscillator Type	Crystal/ceramic oscillator or external clock drive	<ul> <li>Crystal/Ceramic oscillator</li> <li>RC—network oscillator</li> <li>Capacitor oscillator</li> <li>External clock drive (Mask option)</li> </ul>				
Interrupt Function	• Yes	• No				
Standby Function	Yes(Hardware initiation) No	Yes (Software initiation) No				
(Mask option)	(Mask option)					
Low-Voltage Reset Function	No    (Mask option)	<ul><li>Yes (Standard version only)</li><li>No</li></ul>				
Power-On Reset Function	• No	Yes				
Output Port State During Reset	High     (Mask option)	<ul> <li>High</li> <li>Low (R0-R3, R5, R6, R10, R11)</li> </ul>				

## Table 6 Comparison of the MB8850 Series and MB88200 Series (continued)

Device	MB8850 Series	MB88200 Series
Operating Ambient Temperature	• −40°C to +85°C	<ul> <li>Standard version:         <ul> <li>+ -40°C to +85°C(without low-voltage reset function)</li> <li>+ -10°C to +70°C                 (with low-voltage reset function)</li> </ul> </li> <li>A-version:         <ul> <li>+ -30°C to +70°C</li> </ul> </li> </ul>
Supply Current:ActiveStandby	<ul> <li>6mA max. at Vcc=5V, fc=1MHz</li> <li>100μA max. at Vcc=3.5V, fc=0MHz</li> </ul>	<ul> <li>1mA typ. at Vcc=5.0V, fc=1MHz</li> <li>10μA max. at Vcc=3.5V, fc=0MHz</li> </ul>
Number of Instructions	• 70	• 37 : MB88201 • 38 : MB88202
Package Type	<ul> <li>42-pin plastic standard/ shrink DIP: MB8851M/-PSH</li> <li>28-pin plastic standard/ shrink DIP: MB8852M/-PSH MB8854M/-PSH</li> <li>48-pin plastic flat package: MB8855M/56M/58M</li> </ul>	<ul> <li>16-pin plastic standard DIP: MB88201-P,MB88202-P</li> <li>16-pin plastic flat package: MB88201-PF, MB88202-PF</li> </ul>
Members	<ul> <li>MB8851M/-PSH, MB8855M</li> <li>MB8852M/-PSH, MB8856M</li> <li>MB8854M/-PSH, MB8858M</li> <li>A- and L-versions are available for each part above.</li> </ul>	<ul> <li>MB88201-P, MB88202-PF</li> <li>MB88202-P, MB88202-PF</li> <li>A-version is available for each part above.</li> </ul>

# **Product Lineup and Development Tools**

The MB88200 series consists of the MB88201 and MB88202. See Table 7.

Table 7 MB88200 Series Product Line-Up and Development Tools

	MB88201-P/-PF	MB88202-P/-PF			
ROM Size	512 x 8 bits (On-chip mask ROM)	1024 x 8 bits (On-chip mask ROM)			
RAM Size (Directly addressed locations)	16 x 4 bits (0-7)	32 x 4 bits (0-7)			
Register	Total 2: AC, Y	Total 3: AC,X,Y			
I/O Port:  - Input only port  - Output only port  - I/O port  - Control port	Total 12-10 lines 0 0 12-10 0	Total 12-10 lines 0 0 12-10 0			
Output Port Type	<ul> <li>Standard pull-up</li> <li>Standard open-drain</li> <li>Middle-current open-drain</li> <li>12V-interface open-drain</li> <li>(R4-R7 only)</li> <li>(Mask option)</li> </ul>	<ul> <li>Standard pull-up</li> <li>Standard open-drain</li> <li>Middle-current open-drain</li> <li>12V-interface open-drain (R4-R7 only) (Mask option)</li> </ul>			
Stack Depth (Nesting Level)	2 levels	4 levels			
Clock Generator:  - Oscillator type  - Clock frequency (With prescaler)	Yes Crystal RC-network Capacitor External (Mask option) 0.5MHz-2MHz (1MHz-4MHz)	Yes Crystal RC-network Capacitor External (Mask option) 0.5MHz-2MHz (1MHz-4MHz)			
Clock Prescaler (Divide-by-two)	Yes/No (Mask option)	Yes/No (Mask option)			
Reset Function:  - External reset  - Power-on reset function  - Low-voltage reset function	Yes Yes/No (Mask option)	Yes Yes/No (Mask option) High/Low			
Output port level during reset	High/Low (Mask option)	(Mask option)			
Standby Function:  - Initiation method  - Oscillator state during standby	Yes/No (Mask option) Software Stop Stop	Yes/No (Mask option) Software			
<ul><li>Output state</li><li>during standby</li><li>Standby off reset</li><li>function</li></ul>	Hold No	Hold No			

## Table 7 MB88200 Series Product Line-Up and Development Tools (Continued)

	MB88201-P/-PF	MB88202-P/-PF
Instruction Set:  -No. of Instruction -Length/Cycle	37 1/1 or 2/2	38 1/1 or 2/2
Min. Instruction Execution Time	3.0µs min. at 2MHz (Without prescaler)	3.0µs min. at 2MHz (Without prescaler)
Power Supply -Standard version -A-version	Single +5V • 4.5V to 5.5V(Active) 3.5V to 6.0V (Standby) • 3.5V to 5.5V (Active) 3.0V to 6.0V (Standby)	Single +5V • 4.5V to 5.5V (Active) 3.5V to 6.0V (Standby) • 3.5V to 5.5V (Active) 3.0V to 6.0V (Standby)
Operating Ambient Temperature Range	<ul> <li>Standard version:     -40°C to +85°C</li> <li>A-version     -30°C to +70°C</li> </ul>	<ul> <li>Standard version:  -40°C to +85°C</li> <li>A-version</li> <li>-30°C to +70°C</li> </ul>
Process	смоѕ	смоѕ
Package	<ul><li>16-pin DIP</li><li>16-pin flat package</li></ul>	<ul><li>16-pin DIP</li><li>16-pin flat package</li></ul>
Development Tools: - Hardware		keyboard (Common) RS-232C interface (Common)
- Software	SM07620-AXXX : PC-DOS cross ass SM07620-GXXX : PC-DOS host emul	

## **Electrical Characteristics**

Absoluete Maximum Ratings†

_	1		Rating		] ,,_,,		
Parameter	Symbol	Min	Тур	Max	Unit	Remarks	
Supply Voltage		Vcc	Vss-0.3		Vss+7.0	V	
Input Voltage	Vin	Vss-0.3		Vss+7.0	v	Should not exceed Vcc+0.3V.	
Output Voltage	Vouт	Vss-0.3		Vss+7.0	v	Should not exceed Vcc+0.3V.	
		Vss-0.3		Vss+15		For 12V-interface open-drain only.	
Power Dissipation	Po			200	mW		
Operating Ambient	TA	-40		+85	°C	Standard version	
Temperature		-30		+70	°C	A-version	
Storage Temperature	Тѕта	-55		+150	•c		

<sup>†</sup> Permanent device damage may occur if the above ABSOLUTE MAXIMUM RATINGS are exceeded. Functional operation should be restricted to the conditions as detailed in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**Recommended Operating Conditions** 

_			Value			Damanta	
Parameter	Symbol	Min	Тур	Max	Unit	Remarks	
Supply Voltage tion range	Vcc	4.5	5.0	5.5	٧	Active opera-	
tion range		3.5	5.0	6.0	V	Standard version Active operation range	
		3.5		6.0	v	A-Version Standby operation range	
		3.0		6.0	V	Standard version Standby operation range	
	Ves				V	A-version	
Input High Voltage	Viн	0:7•Vcc		Vcc+0.3	<b>V</b>	R-P <u>ort</u>	
	ViHS	0.8•Vcc		Vcc+0.3	V	EX,RESET,START	
Input Low Voltage	VIL	Vss=0.3		0.3•Vcc	V	R-Port	
,	Vils	Vss-0.3		0.2•Vcc	v	EX,RESET,START	
Operating Ambient	TA	-40		+85	°C	Standard version, without	
Temperature		-30		+70	°C	low-voltage reset function  A-version without	
		-10		+70	°C	low-voltage reset function With low-voltage reset functionWWW.DataSheet4U	

## DC Characteristics (Recommended operating conditions unless otherwise noted.)

-				Value			Unit
Parameter	Symbol	Pin/Port	Condition	Min	Тур	Max	Oliik
Output High Voltage	Vон	R-Port (Standard pull-up)	Vcc=4.5V loн=−200µA	2.4			٧
			Vcc=4.5V loн=−10µA	4.0			V
Output Low Voltage	Vol	R-Port (All output options)	Vcc=4.5V loL=1.8mA			0.4	٧
			Vcc=4.5V loL=3.2mA			0.6	٧
		R-Port (Middle-current open-drain)	Vcc=4.5V loL=10mA			2.0	٧
	RESET		Vcc=4.5V loL=3.6mA			0.6	٧
Input Leakage Ін Current			ViH=5.5V			μA 60	
	İst	R-Port (Standard pull-up)	Vcc=5.5V VIL=0.4V		-0.6	-1.6	mA
		Crystal/ceramic oscillation			-10	-20	μΑ
		RC-network/Ca- EX pacitor oscillation	Vcc=5.5V ViL=0.4V		-10	-20	μΑ
		External clock drive				-10	μΑ
		RESET	Vcc=5.5V ViL=0.4V		-20	-60	μΑ
Output Leakage Current (For Open-	ILEAK	R-Port (All open-drains)	Vcc=5.5V Voн=5.5V Output in high-Z		0.1	10	μΑ
Drain Output)	R-Port	Vcc=5.5V (12V-interface open-drain)	Voн=13.2V Output in high-Z			40	μΑ
		Vcc	Vcc=5.0V(Typ.) fc=1MHz (Active) Reset state All outputs open		1	3	m/
	Іссн	Vcc (With standby function)	Vcc=3.5V (Min.) fc=0MHz (Standby) Standby state All outputs open			10	μ.

Note: The "all outputs" include not only "output-only port pins", but also "I/O port pins".

## AC Characteristics (Recommended operating conditions unless otherwise noted.)

				Va	lue	l	l	
Parameter	Symbol	Pin	Condition	Min Max		Unit	Remarks	
Clock Frequency	fc	EX, X	Crystal/ceramic, RC-network, C	0.5	2.0		Without prescale	
,		OSC or external clock drive: Figures 4 and 5		1.0	4.0		With prescaler	
Clock Cycle Time	teye	EX, X	Figures 4 and 5	0.5	2.0	μs		
Input Clock	PwoH,	EX	External clock drive:	225		ns	Without prescale	
Pulse Width	PwaL	EX	Figures 4 and 5	100		113	With prescaler	
Input Clock Rise/Fall	t <sub>cr,</sub>		External clock					
Time	ter	EX	drive: Figures 4 and 5	5	100	ns		

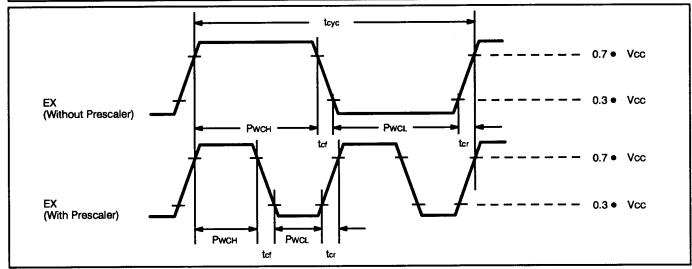


Figure 4. Clock Timing

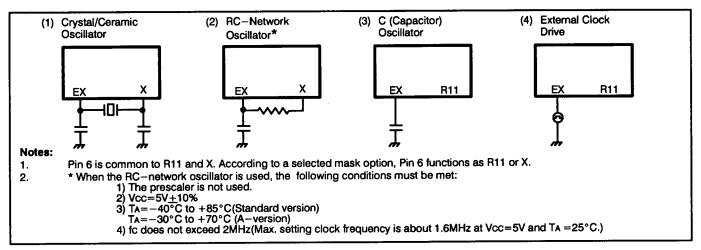


Figure 5. Clock Circuit Configurations

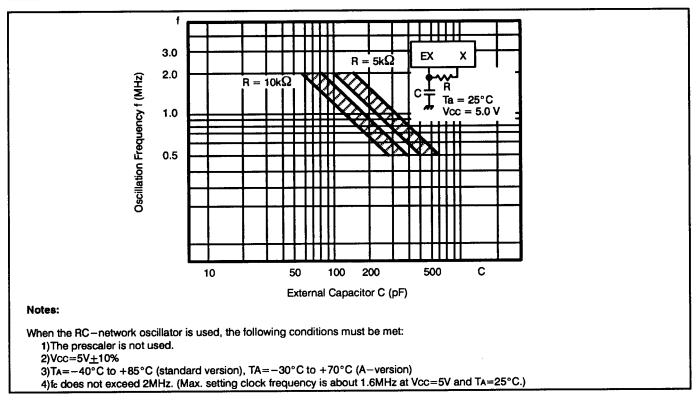


Figure 6. RC-Network Oscillator Characteristics (Example)

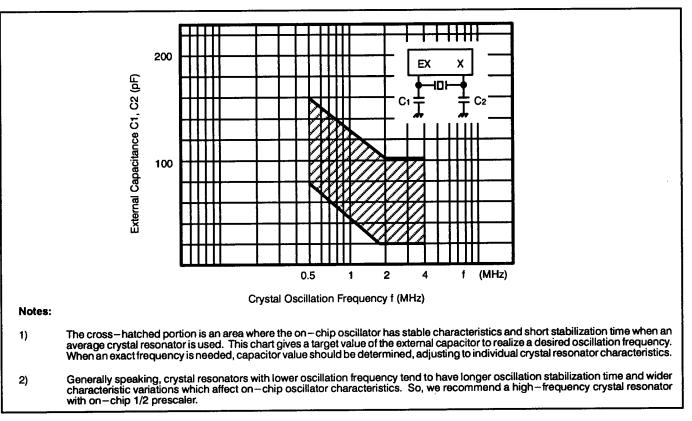


Figure 7. Crystal Oscillator Characteristics (Example)

# Power-on Reset (Built-in) Characteristics (Recommended operating conditions otherwise noted)

_			Va	Values		Domaska
Parameter	meter Symbol Conditions Min Max	Max	Unit	Remarks		
Power Supply Rise Time	tr	Figure 8	0.05	50	ms	Required for operation of the power—on reset circuit
Power Supply Shout-off Time	toff	Figure 8	1	1		Required for accurate circuit operation repeatability

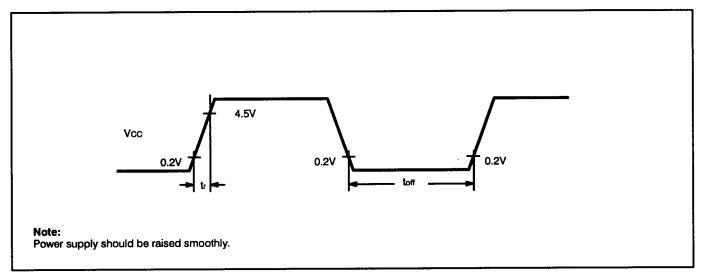
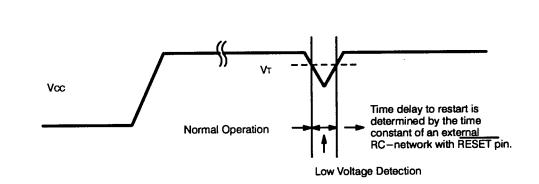


Figure 8. Power-On Reset Timing

## Low Voltage Reset (Mask Option) Characteristics (Standard version only)

 $(Vcc=+5V\pm10\%, Vss=0V, Ta=-10^{\circ}C \text{ to } +70^{\circ}C)$ 

				Value			Domonko
Parameter	Symbol	Pin	Max	Тур	Max	Unit	Remarks
Detection Voltage	<b>V</b> T	Vcc	2.0		4.5	٧	Reset is operational at less than Vt.
Supply Voltage Rise/Fall Slope	Δt/Δν	Vcc	0.01			ms/V	



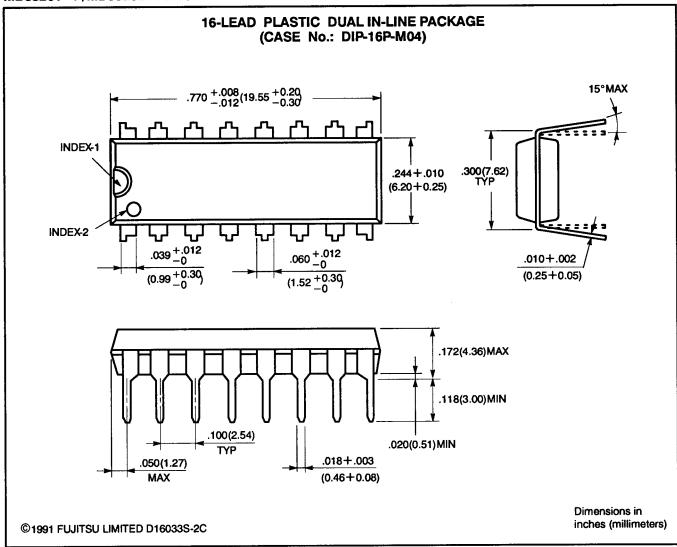
#### Notes:

- 1. The above low-voltage reset spec is guaranteed over the ambient temperature range from -10°C to +70°C, while the other electrical specs are guaranteed over the temperature range from -40°C to +85°C. Therefore, when the low-voltage reset function is implemented on the chip, the whole operating ambient temperature range is reduced to the range from -10°C to +70°C.
- 2. The low-voltage reset function is disabled during the standby mode.

Figure 8. Low-Voltage Reset Characteristics

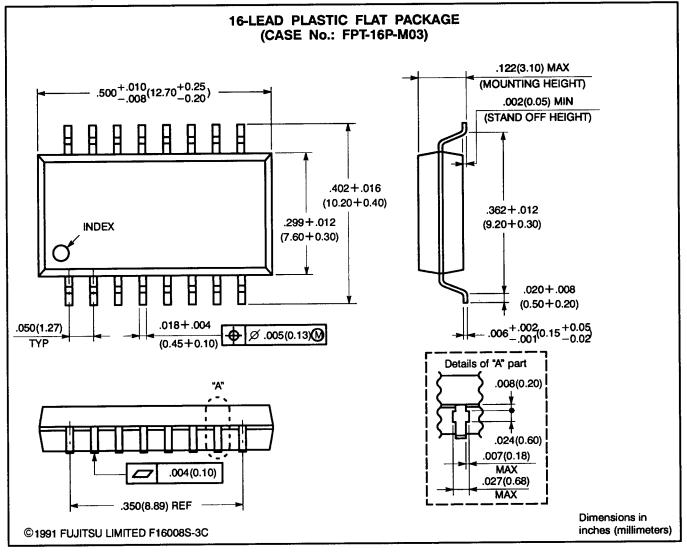
# **Package Dimensions**

## MB88201-P/MB88202-P: 16-PIN PLASTIC DIP



## **Package Dimensions**

## MB88201-PF/MB88202-PF: 16-PIN PLASTIC FLAT PACKAGE



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